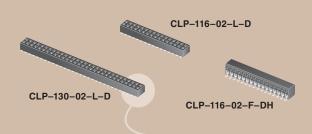


(1,27mm) .050"

CLP SERIES





OW PROFILE DUAL WIPE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

Insulator Material: Black Liquid Crystal Polymer

Contact Material: Phosphor Bronze **Plating:** Sn or Au over 50µ" (1,27µm) Ni

Current Rating: 1.75A @ 80°C ambient Operating Temp Range:

-55°C to +125°C Contact Resistance: 10 mΩ max

Insertion Depth: Top Entry = (1,40mm) .055" minimum, Bottom Entry = (2,41mm) .095" minimum plus board thickness DH Entry = (2,31mm) .091' to (2.67mm) .105" Insertion Force:

(Single contact only) 3.8oz (1,05N) average Normal Force: 60 grams (0,59N) average Withdrawal Force:

(Single contact only) 2oz (0,56N) average

Max Cycles: 100 with 10µ" (0,25µm) Au RoHS Compliant: Yes

Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (02-35) (0,15mm) .006" max (36-50)

ALSO AVAILABLE

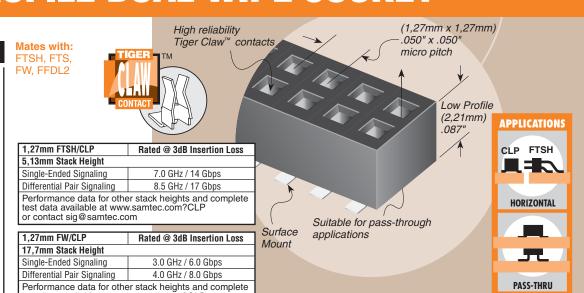
Single row available. (Mates with FTS Series) Call Samtec.

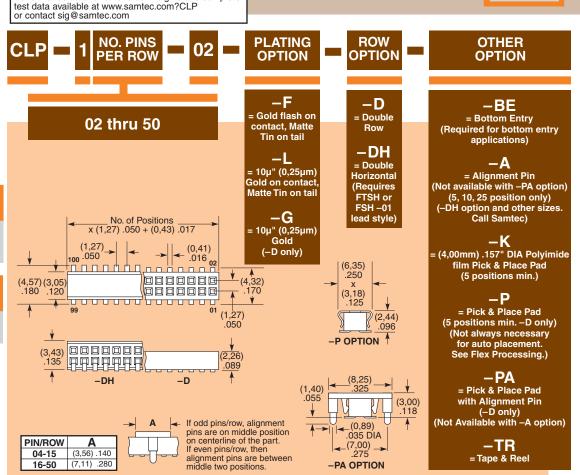
APPLICATION SPECIFIC OPTION

Single row options available. Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard. non-returnable.





Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM